

**CoolMOS™ Power Transistor**
**Features**

- Lowest figure-of-merit  $R_{ON} \times Q_g$
- Extreme dv/dt rated
- High peak current capability
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Worldwide best  $R_{DS,on}$  in TO262 (I<sup>2</sup>Pak)
- Ultra low gate charge

**CoolMOS™ 900V is designed for:**

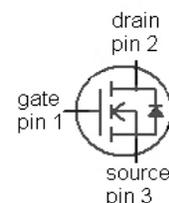
- Quasi Resonant Flyback / Forward topologies
- PC Silverbox and consumer applications
- Industrial SMPS

**Product Summary**

$V_{DS} @ T_J=25^\circ\text{C}$	900	V
$R_{DS(on),max} @ T_J=25^\circ\text{C}$	0.34	$\Omega$
$Q_{g,typ}$	94	nC

**PG-TO262**


Type	Package	Marking
IPI90R340C3	PG-TO262	9R340C


**Maximum ratings, at  $T_J=25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	$I_D$	$T_C=25^\circ\text{C}$	15	A
		$T_C=100^\circ\text{C}$	9.5	
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	$T_C=25^\circ\text{C}$	34	
Avalanche energy, single pulse	$E_{AS}$	$I_D=3.1\text{ A}, V_{DD}=50\text{ V}$	678	mJ
Avalanche energy, repetitive $t_{AR}$ <sup>2),3)</sup>	$E_{AR}$	$I_D=3.1\text{ A}, V_{DD}=50\text{ V}$	1	
Avalanche current, repetitive $t_{AR}$ <sup>2),3)</sup>	$I_{AR}$		3.1	A
MOSFET dv/dt ruggedness	dv/dt	$V_{DS}=0\dots400\text{ V}$	50	V/ns
Gate source voltage	$V_{GS}$	static	$\pm 20$	V
		AC ( $f>1\text{ Hz}$ )	$\pm 30$	
Power dissipation	$P_{tot}$	$T_C=25^\circ\text{C}$	208	W
Operating and storage temperature	$T_J, T_{stg}$		-55 ... 150	$^\circ\text{C}$

**Maximum ratings, at  $T_J=25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous diode forward current	$I_S$	$T_C=25\text{ }^\circ\text{C}$	9.2	A
Diode pulse current <sup>2)</sup>	$I_{S,pulse}$		34	
Reverse diode $dv/dt$	$dv/dt$		4	V/ns

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Thermal characteristics**

Thermal resistance, junction - case	$R_{thJC}$		-	-	0.6	K/W
Thermal resistance, junction - ambient	$R_{thJA}$	leaded	-	-	62	
Soldering temperature, wavesoldering only allowed at leads	$T_{sold}$	1.6 mm (0.063 in.) from case for 10 s	-	-	260	$^\circ\text{C}$

**Electrical characteristics, at  $T_J=25\text{ }^\circ\text{C}$ , unless otherwise specified**
**Static characteristics**

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$	900	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=1\text{ mA}$	2.5	3	3.5	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=900\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^\circ\text{C}$	-	-	2	$\mu\text{A}$
		$V_{DS}=900\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ }^\circ\text{C}$	-	20	-	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=9.2\text{ A}, T_j=25\text{ }^\circ\text{C}$	-	0.28	0.34	$\Omega$
		$V_{GS}=10\text{ V}, I_D=9.2\text{ A}, T_j=150\text{ }^\circ\text{C}$	-	0.76	-	
Gate resistance	$R_G$	$f=1\text{ MHz}$ , open drain	-	1.3	-	$\Omega$

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics**

Input capacitance	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=100\text{ V},$ $f=1\text{ MHz}$	-	2400	-	pF
Output capacitance	$C_{oss}$		-	120	-	
Effective output capacitance, energy related <sup>5)</sup>	$C_{o(er)}$	$V_{GS}=0\text{ V}, V_{DS}=0\text{ V}$ to 500 V	-	71	-	
Effective output capacitance, time related <sup>6)</sup>	$C_{o(tr)}$		-	280	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=400\text{ V},$ $V_{GS}=10\text{ V}, I_D=9.2\text{ A},$ $R_G=23.1\ \Omega$	-	70	-	ns
Rise time	$t_r$		-	20	-	
Turn-off delay time	$t_{d(off)}$		-	400	-	
Fall time	$t_f$		-	25	-	

**Gate Charge Characteristics**

Gate to source charge	$Q_{gs}$	$V_{DD}=400\text{ V}, I_D=9.2\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	11	-	nC
Gate to drain charge	$Q_{gd}$		-	41	-	
Gate charge total	$Q_g$		-	94	tbd	
Gate plateau voltage	$V_{plateau}$		-	4.6	-	V

**Reverse Diode**

Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=9.2\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.8	1.2	V
Reverse recovery time	$t_{rr}$	$V_R=400\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	510	-	ns
Reverse recovery charge	$Q_{rr}$		-	11	-	$\mu\text{C}$
Peak reverse recovery current	$I_{rrm}$		-	41	-	A

<sup>1)</sup> J-STD20 and JESD22

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{J,max}$

<sup>3)</sup> Repetitive avalanche causes additional power losses that can be calculated as  $P_{AV}=E_{AR} \cdot f$ .

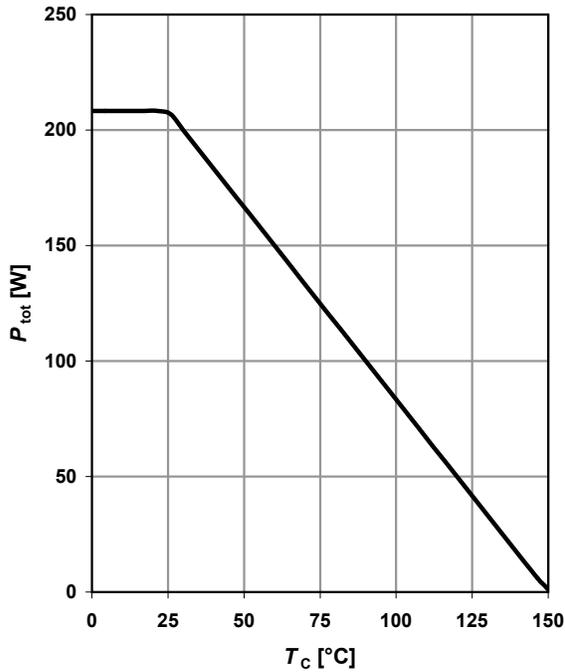
<sup>4)</sup>  $I_{SD} \leq I_D, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DClink}=400\text{ V}, V_{peak} < V_{(BR)DSS}, T_J < T_{J,max}$ , identical low side and high side switch

<sup>5)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 50%  $V_{DSS}$ .

<sup>6)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 50%  $V_{DSS}$ .

**1 Power dissipation**

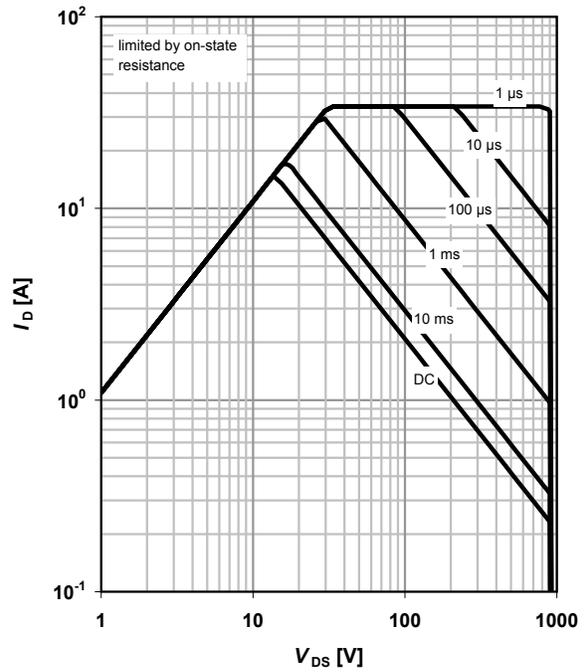
$$P_{tot} = f(T_C)$$



**2 Safe operating area**

$$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$$

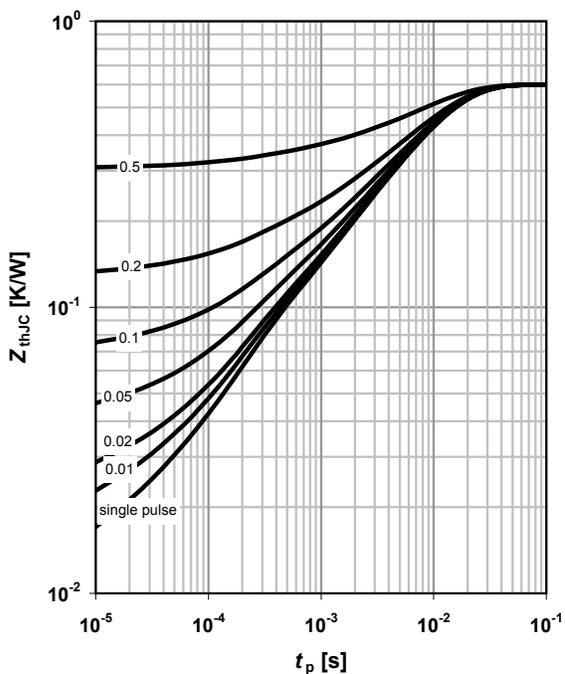
parameter:  $t_p$



**3 Max. transient thermal impedance**

$$Z_{thJC} = f(t_p)$$

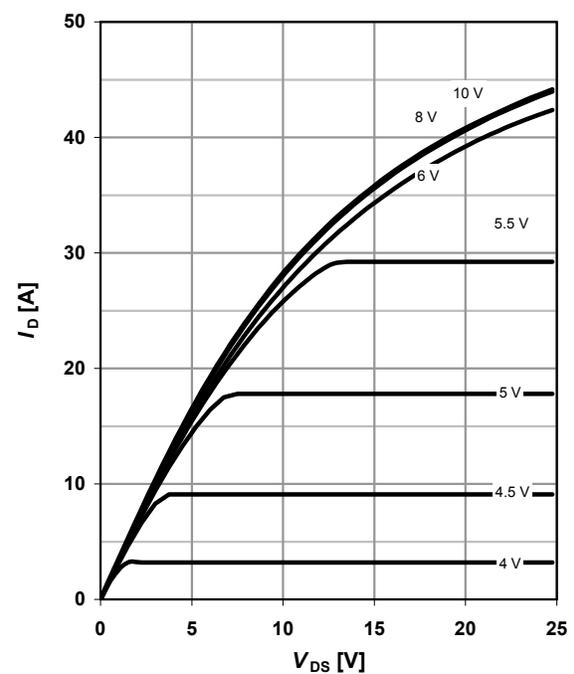
parameter:  $D = t_p / T$



**4 Typ. output characteristics**

$$I_D = f(V_{DS}); T_J = 25\text{ °C}$$

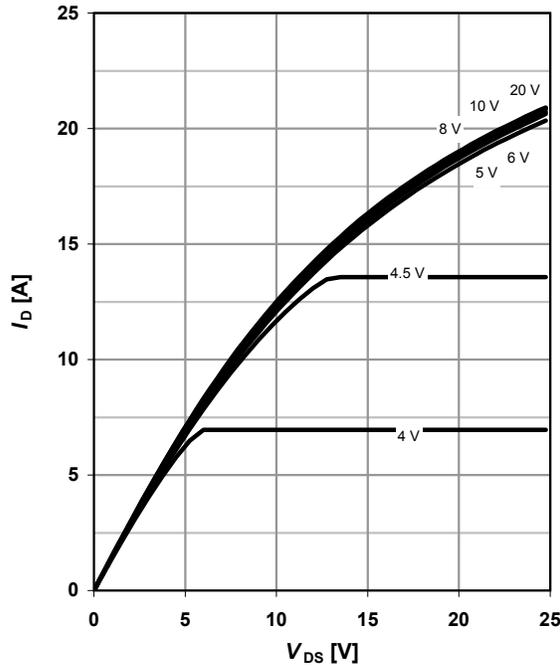
parameter:  $V_{GS}$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_J = 150\text{ }^\circ\text{C}$

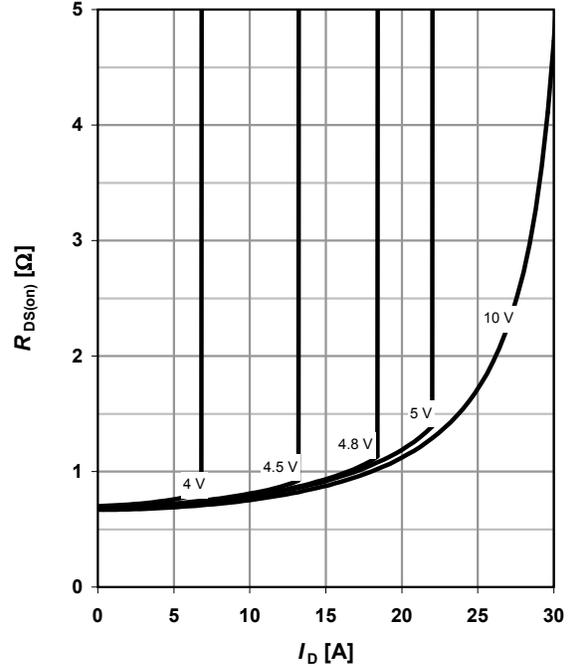
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

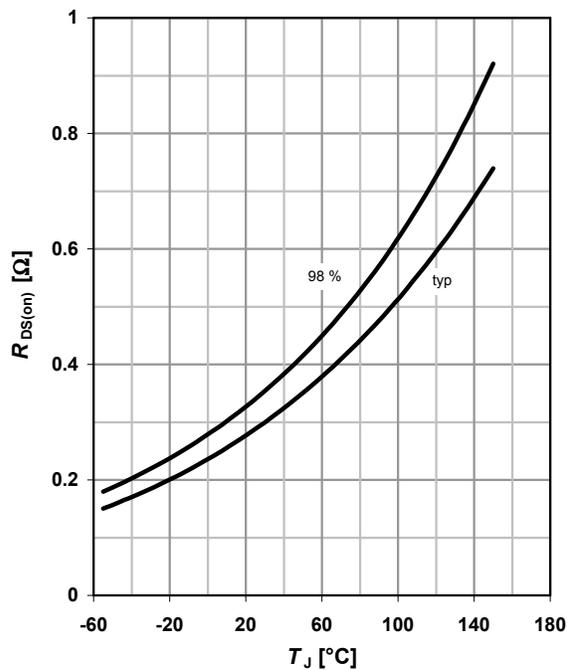
$R_{DS(on)} = f(I_D); T_J = 150\text{ }^\circ\text{C}$

parameter:  $V_{GS}$



**7 Drain-source on-state resistance**

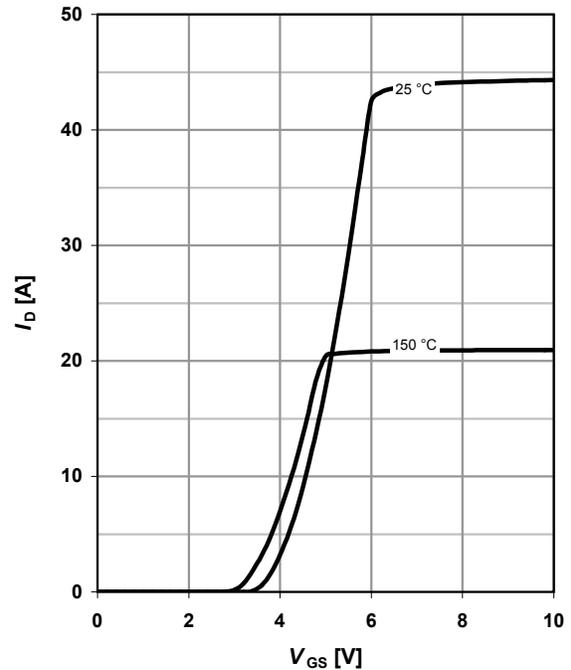
$R_{DS(on)} = f(T_J); I_D = 9.2\text{ A}; V_{GS} = 10\text{ V}$



**8 Typ. transfer characteristics**

$I_D = f(V_{GS}); V_{DS} = 20\text{ V}$

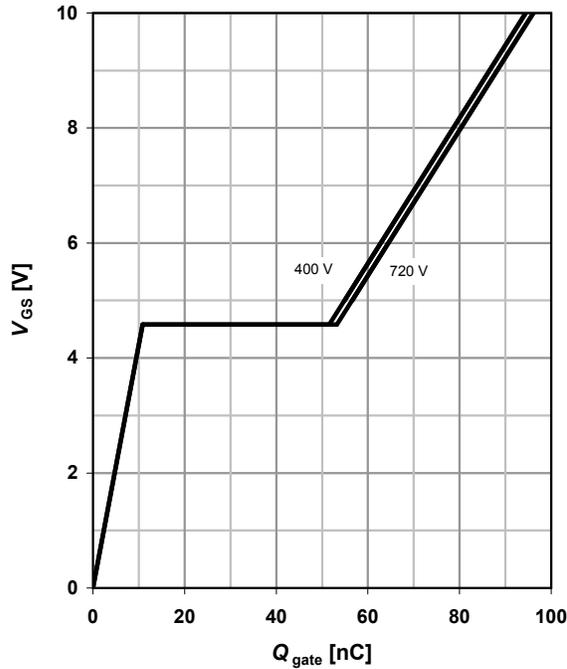
parameter:  $T_J$



**9 Typ. gate charge**

$V_{GS}=f(Q_{gate}); I_D=9.2\text{ A pulsed}$

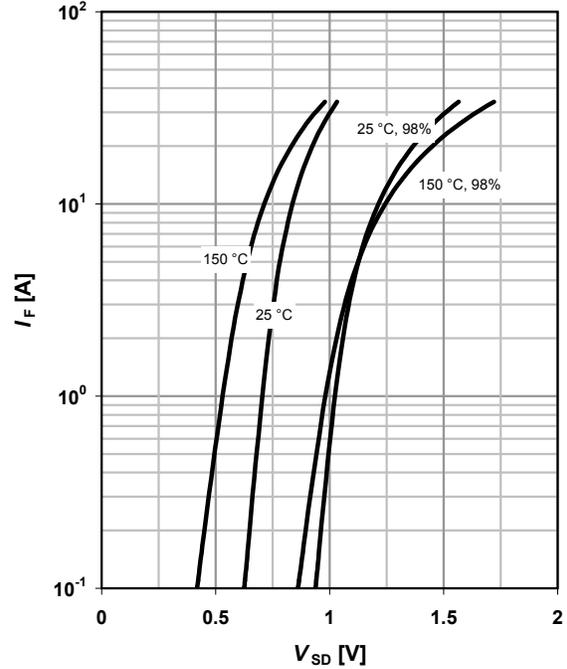
parameter:  $V_{DD}$



**10 Forward characteristics of reverse diode**

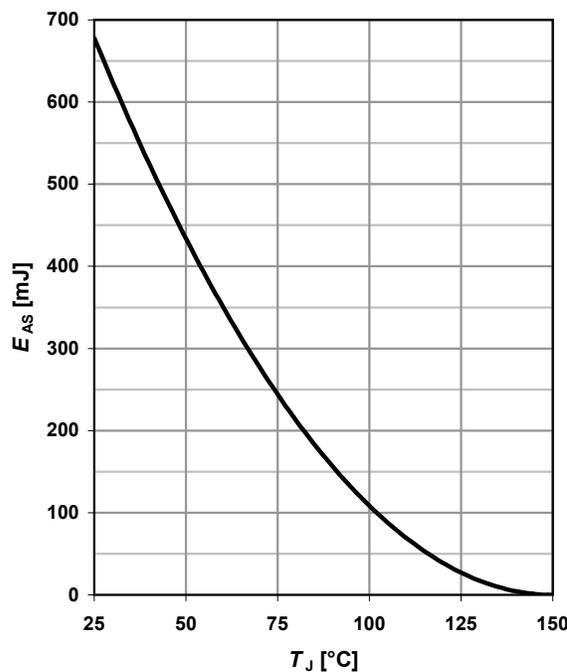
$I_F=f(V_{SD})$

parameter:  $T_J$



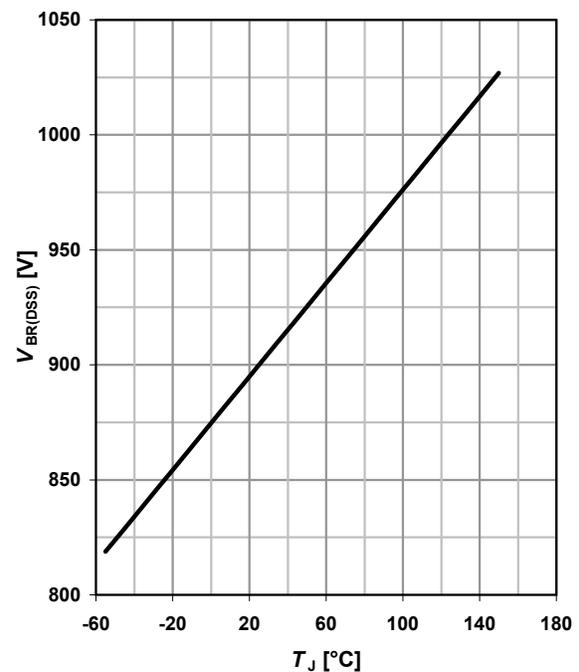
**11 Avalanche energy**

$E_{AS}=f(T_J); I_D=3.1\text{ A}; V_{DD}=50\text{ V}$



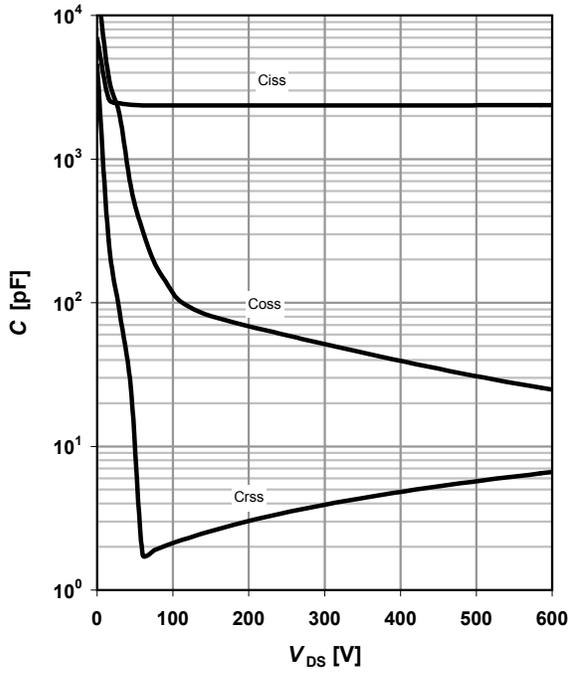
**12 Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_J); I_D=0.25\text{ mA}$



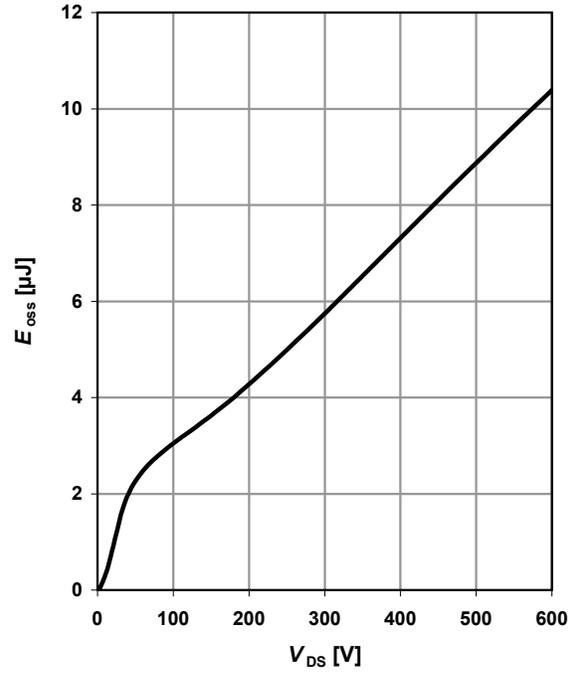
13 Typ. capacitances

$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$

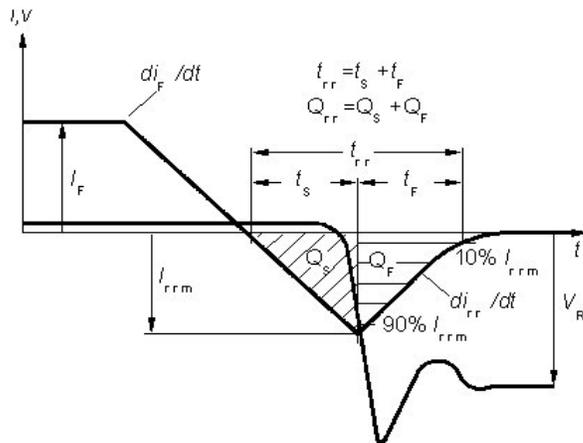


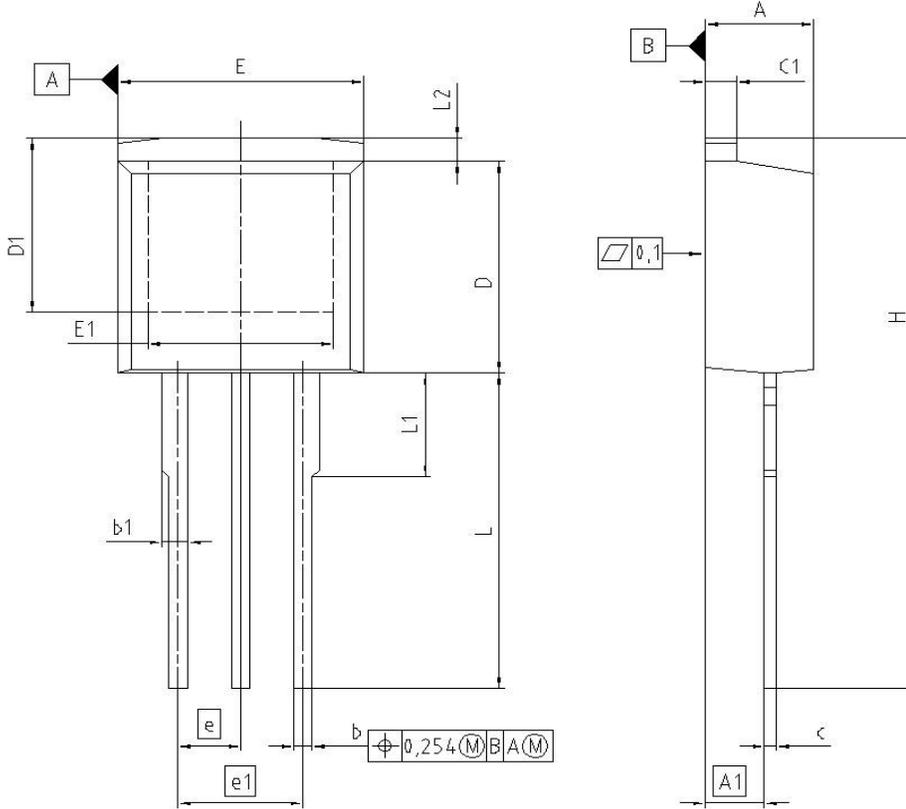
14 Typ. C<sub>oss</sub> stored energy

$E_{oss}=f(V_{DS})$



Definition of diode switching characteristics





DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.300	4.500	0.169	0.177
A1	2.150	2.650	0.085	0.104
b	0.650	0.850	0.026	0.033
b1	0.635	1.400	0.025	0.055
c	0.400	0.600	0.016	0.024
c1	1.170	1.370	0.046	0.054
D	9.050	9.450	0.356	0.372
D1	6.900	7.650	0.272	0.301
E	9.800	10.200	0.386	0.402
E1	7.250	8.600	0.285	0.339
e	2.540		0.100	
e1	5.080		0.200	
N	3		3	
L	13.000	14.000	0.512	0.551
L1	4.350	4.750	0.171	0.187
L2	0.700	1.300	0.028	0.051

REFERENCE JEDEC TO262
SCALE 0 2.5 5mm
EUROPEAN PROJECTION 
ISSUE DATE 01-06-2005
FILE TO262_1

Dimensions in mm/inches

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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